



125M / 155M 1X9-100BASE-BX-U Transceiver
BiDi SC, Tx1310nm FP / Rx1550nm, MMF 2KM, I-Temp
LVPECL Signal Detection

Part Number: F1X9-A2-M35-02Pi



Overview

F1X9-A2-M35-02Pi 1X9 SIP package style transceivers are compliant with the industrial standard specification. The high performance uncooled 1310nm FP transmitter and high sensitivity PIN receiver provide superior performance for Fast Ethernet 100BASE-BX and SONET OC-3 / SDH STM-1 applications up to MMF 2km optical links in Industrial Temperature range.

Applications

- Fast Ethernet 100BASE-BX @125M
- SDH STM-1 / SONET OC-3 @155M

Features

- Compatible with IEEE802.3ah 100BASE-BX
- Compatible with SONET OC-3 IR-1 and SDH STM-1 S-1.1
- Industry Standard 1X9 Footprint
- 1310nm FP transmitter & 1550nm PIN receiver
- Simplex BiDi SC connector
- Single 3.3V Power Supply
- DC-coupled Differential LVPECL inputs and outputs
- LVPECL Signal Detection Output
- Wave Solderable and Aqueous Washable
- Link distance 2km over MM fiber
- Operating Temperature -40~+85°C
- Maximum Power consumption 1W
- RoHS Compliant

Laser Safety

- This is a Class 1 Laser Product complies with 21 CFR 1040.10 and 1040.11 except for conformance with IEC 60825-1 Ed. 3., as described in Laser Notice No. 56, dated May 8, 2019.
- Caution: Use of control or adjustments or performance of procedure other than those specified herein may result in hazardous radiation exposure.



Absolute Maximum Ratings

Parameters	Symbol	Min.	Max.	Unit
Storage Temperature	T _{ST}	-40	+85	°C
Relative Humidity	RH	5	85	%
Supply Voltage	V _{CC}	0	+3.6	V

Recommended Operating Conditions

Parameters	Symbol	Min.	Typ.	Max.	Unit
Case Operating Temperature	T _{OP}	-40		+85	°C
Supply Voltage	V _{CC}	+3.13	+3.3	+3.47	V
Supply Current	I _{CC}			300	mA
Power Consumption	P			1	W
Lead Soldering Limits	T _{sold}			260/10	°C/Sec

Transmitter Electro-optical Characteristics

V_{CC} = 3.13V to 3.47V, T_{OP} = -40 °C to +85 °C

Parameters	Symbol	Min.	Typ.	Max.	Unit	Note
Operating Data Rate	DR		125/155		Mb/s	
Optical Launch Power	P _o	-10		-3	dBm	1
Optical Center Wavelength	λ _c	1270	1310	1350	nm	
Spectral Width (RMS)	Δλ			3	nm	
Optical Extinction Ratio	ER	9			dB	
Optical Eye Mask		IEEE802.3ah and ITU-T G.957				
Rise / Fall Time (20%~80%)	T _r / T _f			2	ns	
Differential Data Input Swing	V _{IN}	400		1800	mV	
Data Input Voltage-Low	V _{IL} -V _{CC}	-2.0		-1.58	V	
Data Input Voltage-High	V _{IH} -V _{CC}	-1.1		-0.74	V	

Note1: The optical power is launched into a 62.5/125μm multi-mode fiber.



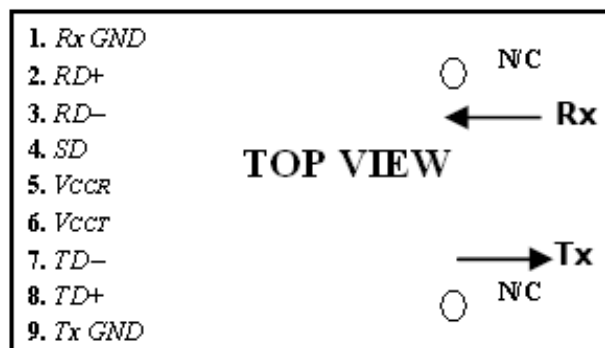
Receiver Electro-optical Characteristics

V_{CC} = 3.13V to 3.47V, T_{OP} = -40 °C to +85 °C

Parameters	Symbol	Min.	Typ.	Max.	Unit	Note
Operating Data Rate	DR		125/155		Mb/s	
Receiver Sensitivity	SEN			-30	dBm	1
Maximum Receive Power	P _{Rx-MAX}	-3			dBm	1
Optical Center Wavelength	λ _C	1530		1570	nm	
Signal Detect Assert	SD _A			-30	dBm	
Signal Detect De-Assert	SD _D	-40			dBm	
Signal Detect Hysteresis	SD _{HY}	0.5		5	dB	
Differential Data Output Swing	V _{OUT}	500		1200	mV	
Data Output Voltage-Low	V _{OL} -V _{CC}	-2.0		-1.58	V	
Data Output Voltage-High	V _{OH} -V _{CC}	-1.1		-0.74	V	

Note1: Measured with a PRBS 2²³-1 test pattern @155Mbps BER<10⁻¹².

Pin Assignment



Pin Description

Pin	Name	Function / Description
1	Rx GND	Receiver Signal Ground
2	RD+	Receiver Data Out
3	RD-	Receiver Data Out Bar
4	SD	Signal Detect (1)
5	VccR	Receiver Power Supply
6	VccT	Transmitter Power Supply
7	TD-	Transmitter Data In Bar
8	TD+	Transmitter Data In
9	Tx GND	Transmitter Signal Ground

Note1: Signal Detect is a basic fiber failure indicator. This is a single-ended LVPECL output. As the input optical power is decreased, Signal Detect will switch from high to low (de-assert point) somewhere between sensitivity and the no light input level. As the input optical power is increased from very low levels, Signal Detect will switch back from low to high (assert point).



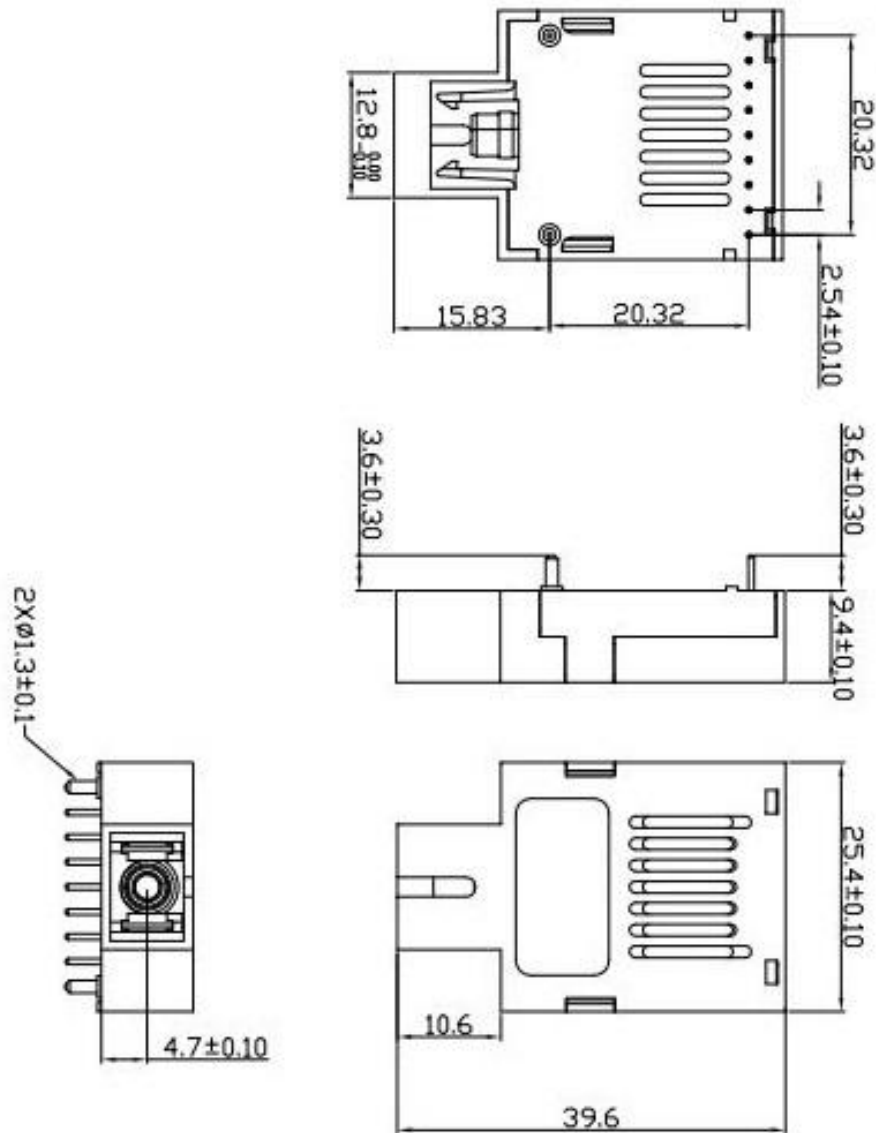
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The diagram shows the internal connections of the transceiver. On the left, the TX pin (pin 9) is connected to TX Vcc through a network of resistors (R1, R3) and capacitors (C5). The TD+ and TD- signals are connected to pins 8 and 7 respectively. The RX pin (pin 1) is connected to RX Vcc through a network of resistors (R9, R7) and capacitors (C6). The RD+, RD-, and SD signals are connected to pins 2, 3, and 4 respectively. The RX Vcc and TX Vcc pins are connected to the external Vcc through inductors (L1, L2) and capacitors (C1, C2, C3, C4). The diagram also indicates 'No internal connection' for pins 6, 5, 4, 3, 2, 1, 8, 7, 6, 5, 4, 3, 2, 1.

R1=R3=R5=R7=R9=130Ω
R2=R4=R6=R8=R10=82Ω
C1=C2=C3=C5=C6=0.1uF
C4=10uF L1=L2=1uH



Mechanical Dimensions



(All Dimensions are ±0.20mm Unless Otherwise Specified, Unit: mm)



Ordering Information

Part No.	Tx	Rx	Conn.	I/O	SD	Link	Voltage	Temp.
F1X9-A2-M35-02Pi	1310nm	1530nm ~ 1570nm	BiDi SC	DC/DC	LVPECL	MMF 2km	3.3V	-40~+85°C

Note: Distances are indicative only. To calculate a more precise link budget based on specific conditions in your application, please refer to the optical characteristics.